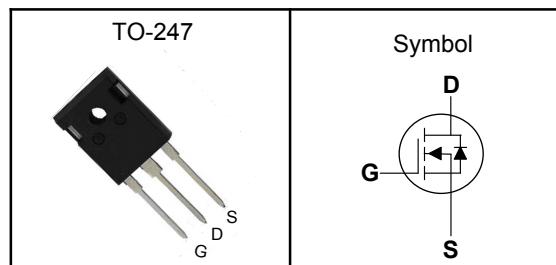


600V Super Junction Power MOSFET

Features

- Low drain-source on-resistance: $R_{DS(ON)}=0.06\Omega(\text{typ})$
- Easy to control gate switching
- Enhancement mode: $V_{th} = 2.5 \text{ to } 4.5\text{V}$
- 100% avalanche tested
- RoHS compliant

Pin Description



Applications

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)
- Charger, Lighting

V_{DSS}	600	V
$R_{DS(ON)-\text{Typ}}$	60	$\text{m}\Omega$
I_D	43	A

Absolute Maximum Ratings ($T_C=25^\circ\text{C}$, Unless Otherwise Noted)

Symbol	Parameter		Rating	Unit
V_{DSS}	Drain-Source Voltage		600	V
V_{GSS}	Gate-Source Voltage		± 30	V
T_J	Maximum Junction Temperature		-55 to 150	$^\circ\text{C}$
T_{STG}	Storage Temperature Range		-55 to 150	$^\circ\text{C}$
E_{AS}	Single Pulse Avalanche Energy		960	mJ
$I_{DM}^{①}$	300 μs Pulse Drain Current Tested		129	A
I_D	Continuous Drain Current	$T_C=25^\circ\text{C}$	43	A
	Continuous Drain Current	$T_C=100^\circ\text{C}$	27	A
P_D	Maximum Power Dissipation	$T_C=25^\circ\text{C}$	236	W
I_{AS}	Avalanche Current		8	A
dv/dt	MOSFET dv/dt ruggedness, $V_{DS} = 0 \dots 480\text{V}$		50	V/ns
	Reverse diode dv/dt $V_{DS}=0 \dots 400\text{V}$, $ISD \leq ID$		15	

Thermal Characteristics

Symbol	Parameter		Rating	Unit
$R_{\theta JA}^{③}$	Thermal Resistance Junction-Ambient ₁		62.5	$^\circ\text{C}/\text{W}$
$R_{\theta JC}$	Thermal Resistance Junction-Case ₁		0.53	$^\circ\text{C}/\text{W}$

Note ① : Max. current is limited by bonding wire.

Note ② : UIS tested and pulse width are limited by maximum junction temperature 150°C .

Note ③ : Surface Mounted on 1in² FR-4 board with 1oz.



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600V Super Junction Power MOSFET

Electrical Characteristics ($T_J=25^\circ\text{C}$, Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
Static Electrical Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_{\text{D}}=1\text{mA}$	600	---	---	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{DS}}=600\text{V}$, $V_{\text{GS}}=0\text{V}$	---	---	1	μA
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}$, $I_{\text{D}}=2.5\text{mA}$	2.5	---	4.5	V
I_{GSS}	Gate Leakage Current	$V_{\text{GS}}=\pm 30\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 100	nA
$R_{\text{DS}(\text{ON})}$	Drain-Source On-state Resistance	$V_{\text{GS}}=10\text{V}$, $I_{\text{D}}=20\text{A}$	---	60	70	$\text{m}\Omega$
Dynamic Characteristics^⑤						
C_{iss}	Input Capacitance	$V_{\text{GS}}=0\text{V}$, $V_{\text{DS}}=100\text{V}$, Freq.=1MHz	---	3200	---	pF
C_{oss}	Output Capacitance		---	140	---	
C_{rss}	Reverse Transfer Capacitance		---	3.7	---	
$T_{\text{d}(\text{on})}$	Turn-on Delay Time	$V_{\text{GS}}=10\text{V}$, $V_{\text{DD}}=400\text{V}$, $I_{\text{D}}=20\text{A}$, $R_{\text{G}}=3\Omega$	---	23	---	nS
T_r	Turn-on Rise Time		---	15	---	
$T_{\text{d}(\text{off})}$	Turn-off Delay Time		---	88	---	
T_f	Turn-off Fall Time		---	10	---	
Q_g	Total Gate Charge	$V_{\text{GS}}=10\text{V}$, $V_{\text{DD}}=400\text{V}$, $I_{\text{D}}=20\text{A}$	---	76	---	nC
Q_{gs}	Gate-Source Charge		---	22	---	
Q_{gd}	Gate-Drain Charge		---	25	---	
R_g	Gate resistance	$f=1\text{ MHz}$, open drain	---	1	---	Ω
Source-Drain Characteristics						
I_s	Continuous Source Current		---	---	43	A
ISM	Maximum Pulsed Drain-Source Diode Forward Current		---	---	129	A
V_{SD}	Diode Forward Voltage	$I_s=20\text{A}$, $V_{\text{GS}}=0\text{V}$	---	---	1.4	V
t_{rr}	Reverse recovery time	$I_s=20\text{A}$, $V_{\text{GS}}=0\text{V}$ $dI/dt=100\text{A}/\mu\text{s}$	---	420	---	ns
Q_{rr}	Reverse recovery charge		---	7.4	---	nC
I_{rrm}	Peak Reverse Recovery Current		---	35	---	A

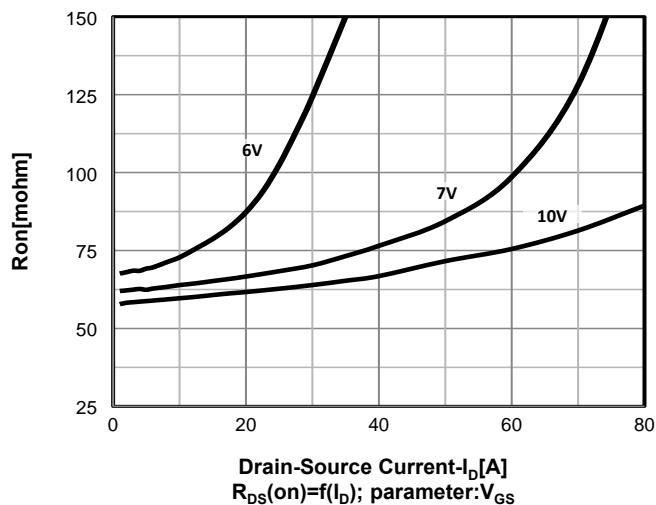
Note ④: Pulse test (pulse width $\leq 300\text{us}$, duty cycle $\leq 2\%$).

Note ⑤: Guaranteed by design, not subject to production testing.

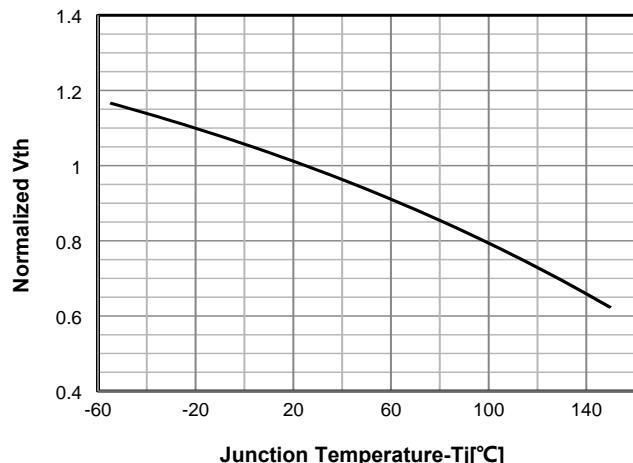
600V Super Junction Power MOSFET

Typical Characteristics

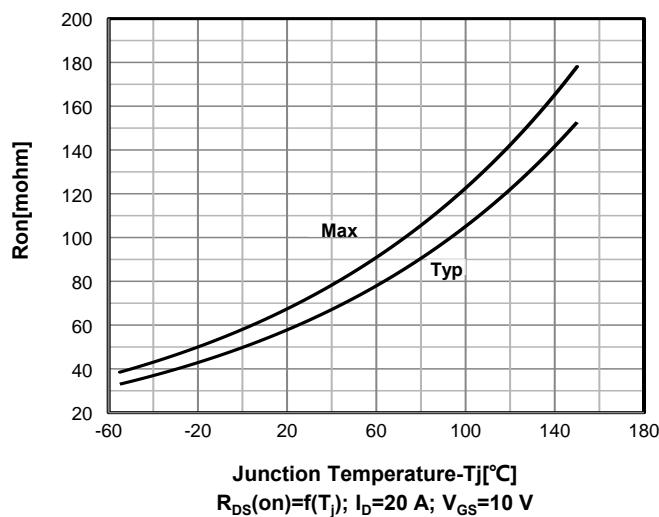
Typ. drain-source on-state resistance



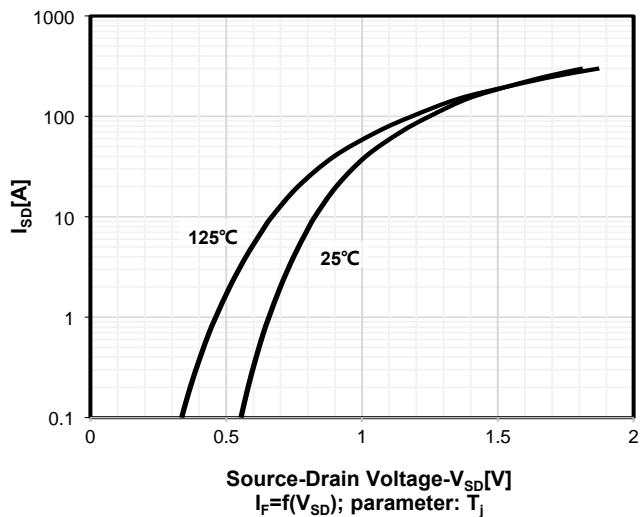
Normalized $V_{GS(th)}$ characteristics



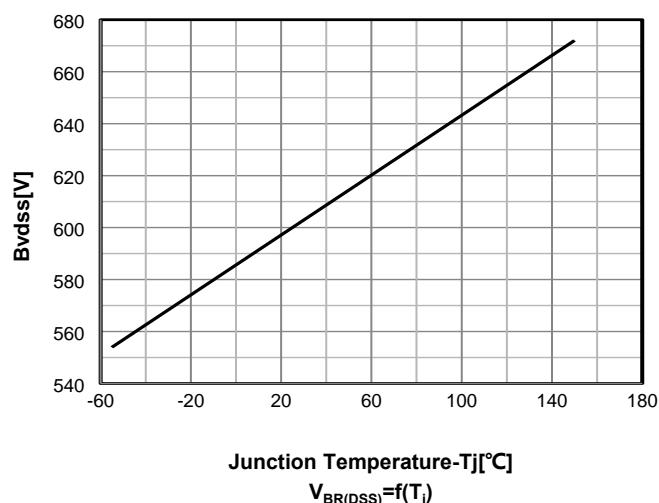
On-resistance vs temperature



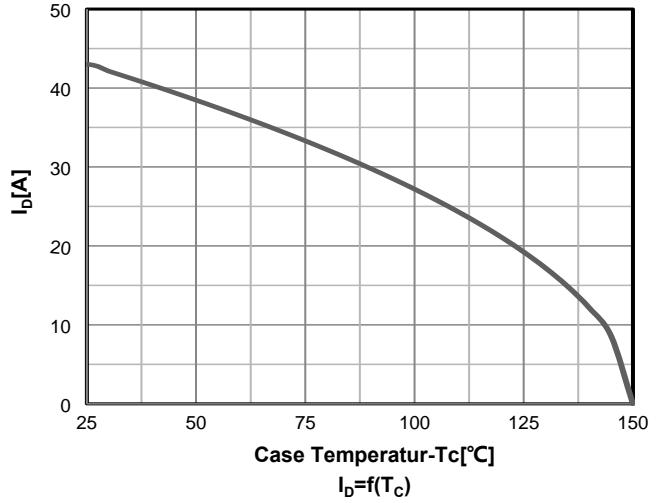
Forward characteristics of reverse diode



Drain-source breakdown voltage

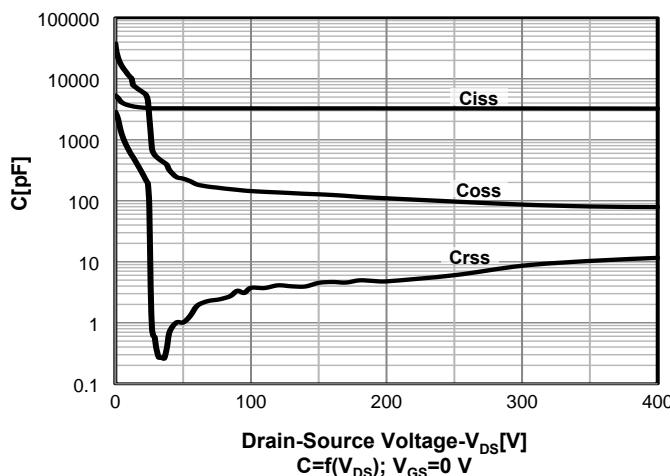


Drain current vs temperature

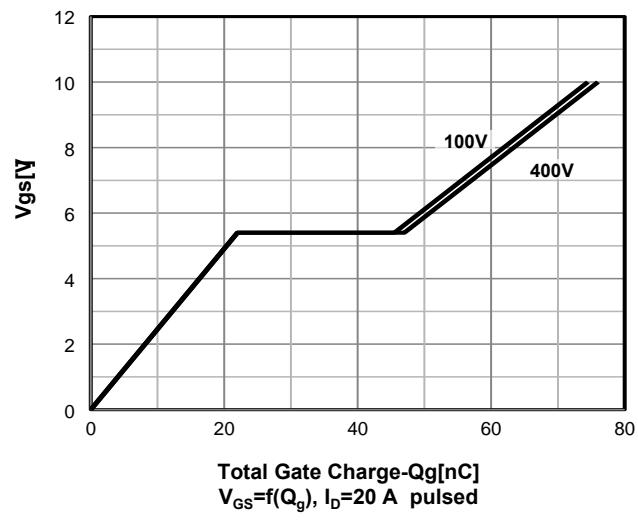


600V Super Junction Power MOSFET

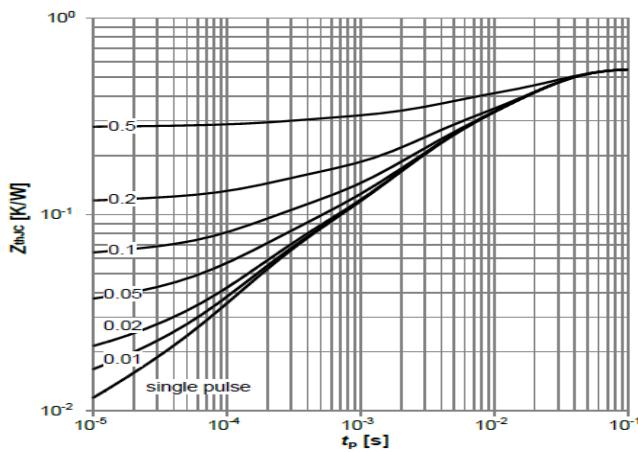
Typ. capacitances



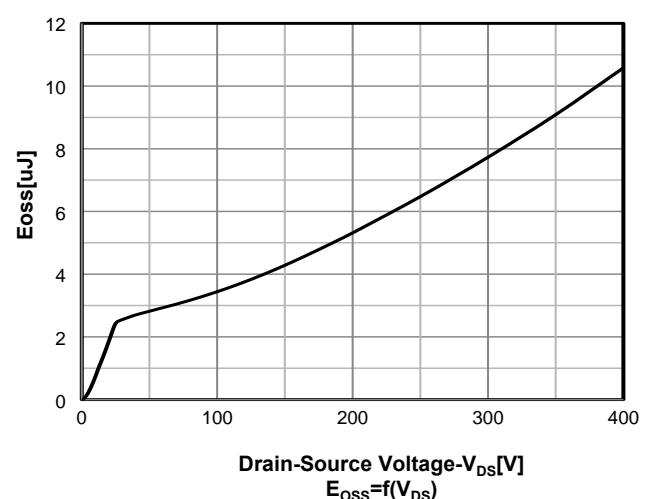
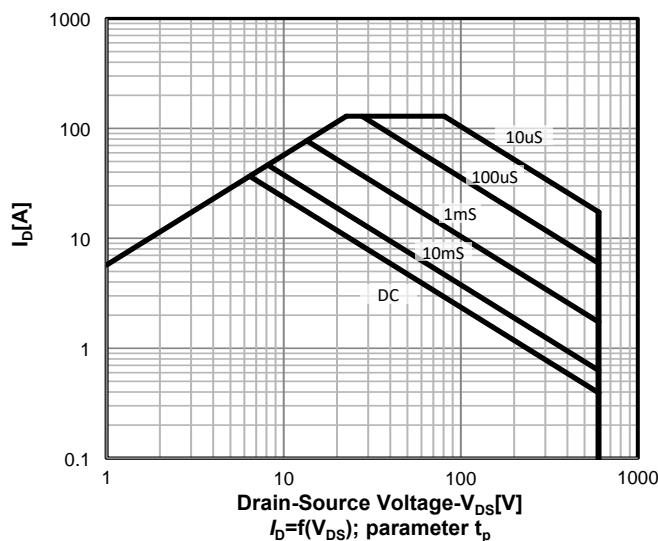
Typ. gate charge characteristics



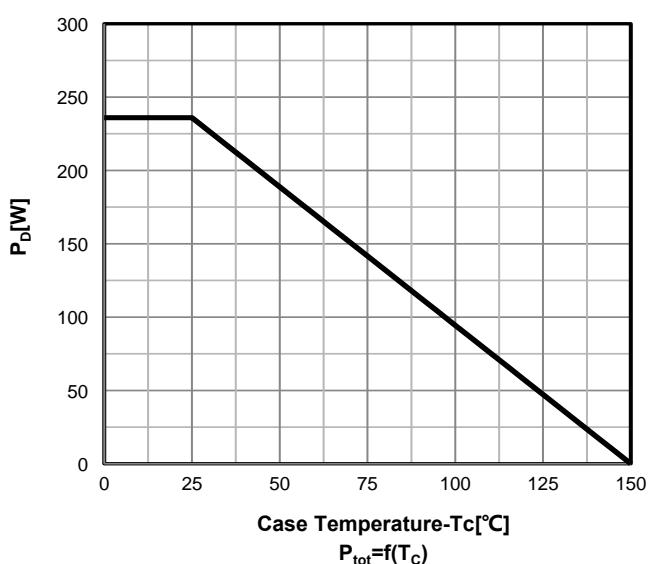
Max. transient thermal impedance parameter: $D=t_p/T$



Safe operating area $TC=25$ °C
 TO-247

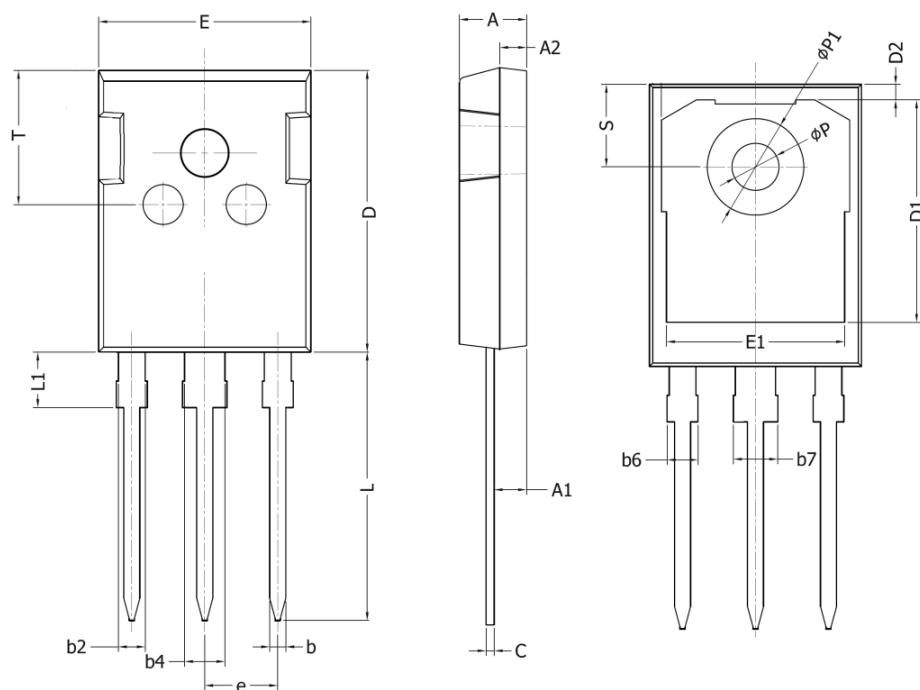


Power dissipation



600V Super Junction Power MOSFET

TO-247 Package Outline Dimensions



Symbol	Dimensions In Millimeters	
	Min.	Max.
A	4.90	5.20
A1	2.31	2.51
A2	1.9	2.1
b	1.16	1.26
b2	1.96	2.06
b4	2.96	3.06
b6	-	2.25
b7	-	3.25
C	0.59	0.66
D	20.90	21.20
D1	16.25	16.85
D2	1.05	1.35
E	15.75	16.10
E1	13.00	13.60
e	5.436 BSC	
L	19.80	20.20
L1	-	4.30
P	3.40	3.60
P1	7.00	7.40
S	6.05	6.25
T	9.80	10.20



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600V Super Junction Power MOSFET

印字说明

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FS60R070CG

AABBCC

第一行标记为物料型号代码

第二行为AA为内部识别码，BB为表示年份，例如22即表示2022年，CC表示周期，例如01即表示第一周；
2201即表示2022年第一周生产。